



Material Content Data Sheet



Sales Product Name		BAW 56S H6327		Issued		25. September 2017		
MA#		MA000844150						
Package		PG-SOT363-6-3		Weight*		6.46 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		13	
	noble metal	gold	7440-57-5	0.008	0.12		1250	
	inorganic material	silicon	7440-21-3	0.069	1.07	1.19	10680	11943
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		96	
	non noble metal	titanium	7440-32-6	0.003	0.05		481	
	non noble metal	chromium	7440-47-3	0.009	0.14		1442	
	non noble metal	copper	7440-50-8	3.093	47.86	48.06	478515	480534
wire	non noble metal	copper	7440-50-8	0.010	0.16	0.16	1554	1554
encapsulation	organic material	carbon black	1333-86-4	0.030	0.46		4628	
	plastics	epoxy resin	-	0.643	9.95		99493	
	inorganic material	silicondioxide	60676-86-0	2.318	35.86	46.27	358637	462758
leadfinish	non noble metal	tin	7440-31-5	0.213	3.30	3.30	32991	32991
plating	noble metal	silver	7440-22-4	0.066	1.02	1.02	10220	10220
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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